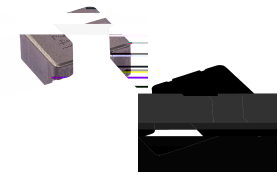
MDA Series

SMD Low Profile High Current Molded Inductor

Size 1350



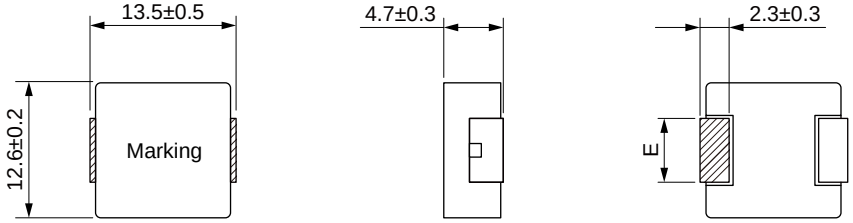
FEATURES

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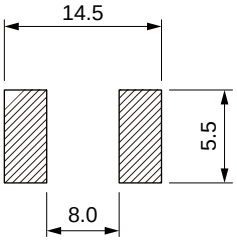
APPLICATION

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Dimensions: [mm]

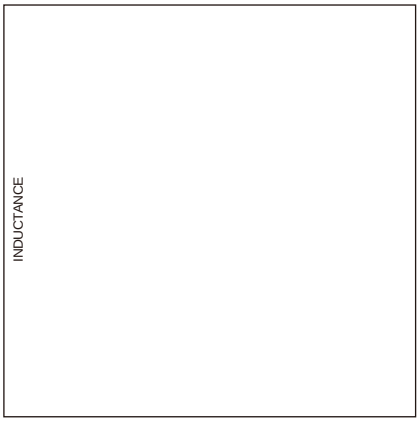


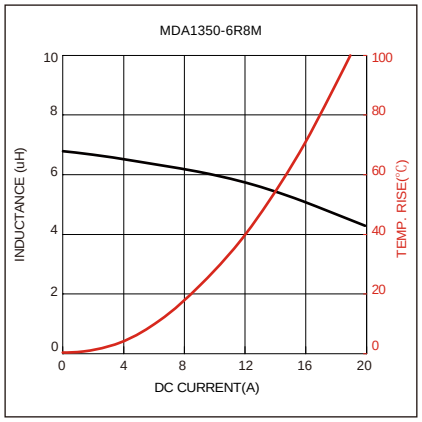
Land Pattern: [mm]DC Resistance Typ.

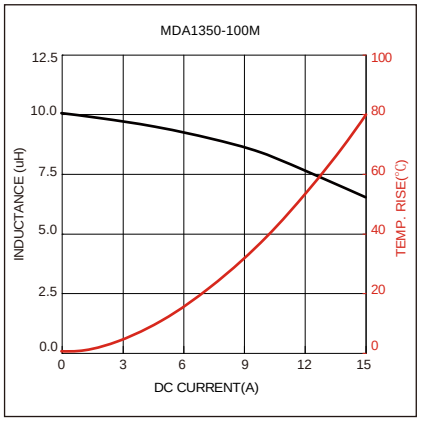


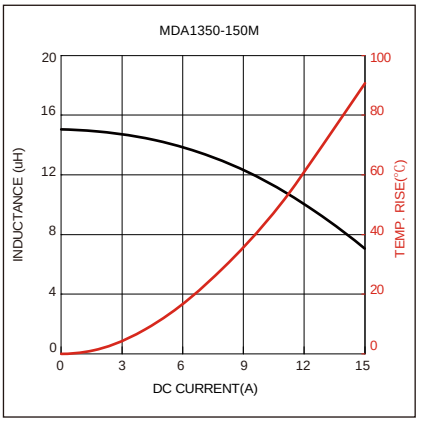
Electrical Properties:

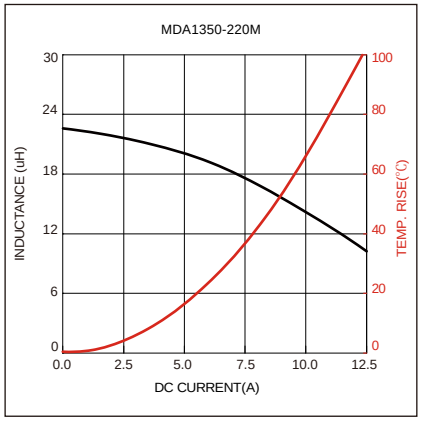
Typical Electrical Characteristics:

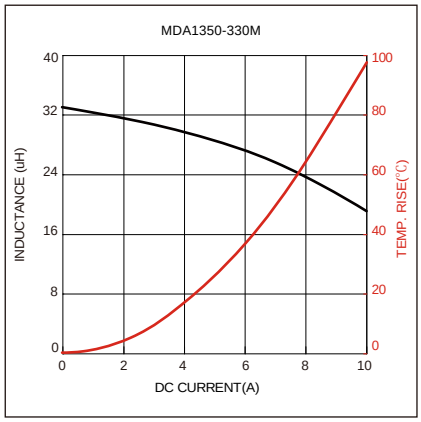


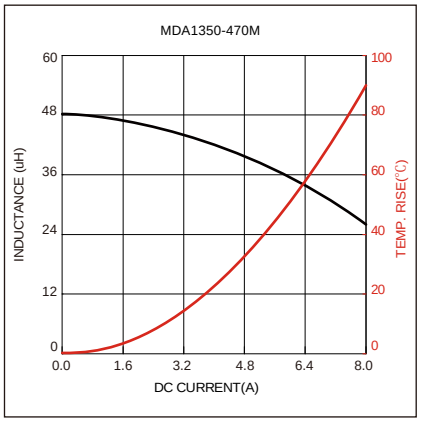

MDA1350-6R8M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0 2 4 6 8 10
0 20 40 60 80 100
0 4 8 12 16 20

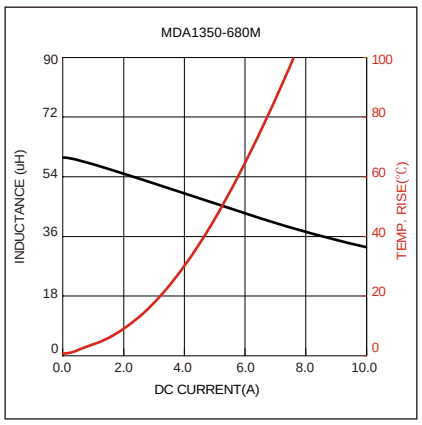

MDA1350-100M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0.0 2.5 5.0 7.5 10.0 12.5
0 20 40 60 80 100
0 3 6 9 12 15


MDA1350-150M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0 4 8 12 16 20
0 20 40 60 80 100
0 3 6 9 12 15

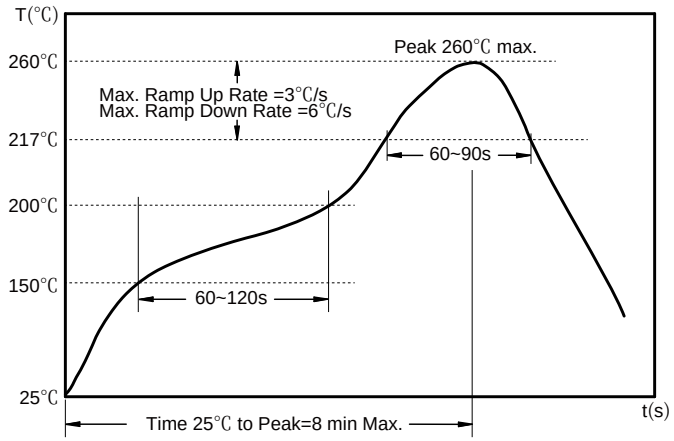

MDA1350-220M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0 6 12 18 24 30
0 20 40 60 80 100
0.0 2.5 5.0 7.5 10.0 12.5


MDA1350-330M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0 8 16 24 32 40
0 20 40 60 80 100
0 2 4 6 8 10


MDA1350-470M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0 12 24 36 48 60
0 20 40 60 80 100
0.0 1.6 3.2 4.8 6.4 8.0


MDA1350-680M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0 18 36 54 72 90
0 20 40 60 80 100
0.0 2.0 4.0 6.0 8.0 10.0

Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

Max temperature: 260℃.

Max time at max temperature: 10 sec.

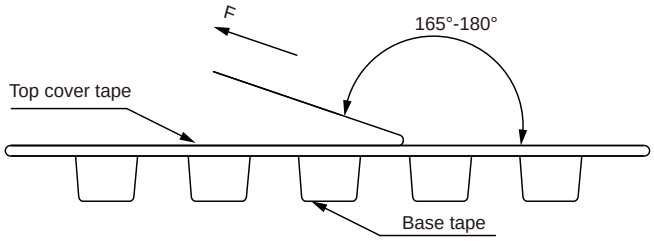
Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension：

Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDA1350	13.1±0.1	14.0±0.1	1.5±0.1	4.0±0.1	16.0±0.1	24.0±0.3	5.4±0.1	1.75±0.1	0.50±0.05

Peel force of top cover tape:

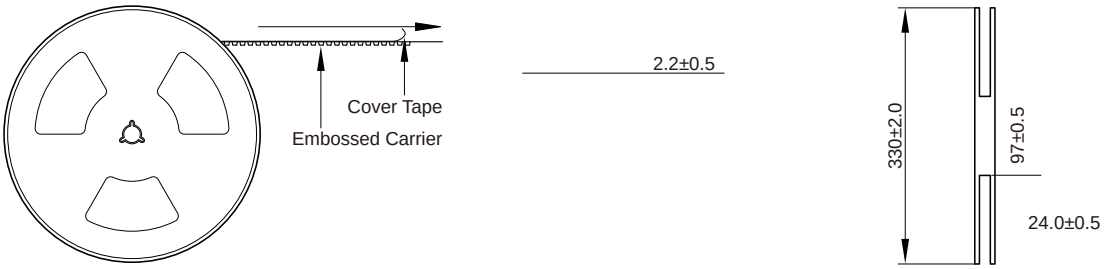


The peel force of top cover tape shall be between 0.1 to 1.3 N

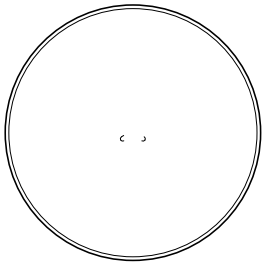
Product Marking:

Marking	KH+Printing（Inductance+period）

Reel Dimension：[mm]



Packaging Quantity:



500 Pcs/Reel

2 Reel /Inner box(1000 Pcs)

2 Inner box/Carton box(2K Pcs)

Cautions and Warnings:

Storage Conditions：

Operation Instructions: